

IR3100 INFO SHEET



NEW

Available in
Spring

InfraRed

IR3100 Infrared BGA Rework Station

Production BGA Installation & Rework Made Easy!

The IR 3100 can easily install and remove BGA, QFN, μ BGA/CSP, Flip Chip and other SMD's. Featuring a 500W infrared (IR) top heater and a 1000W IR bottom preheater, the IR 3100 does not require nozzles. A specially-developed IR sensor provides non-contact, real-time, closed-loop temperature control throughout the reflow process. A Sodr-Cam Reflow Camera comes standard, allowing you to watch the entire reflow process in real time. The IR 3100's newly designed Windows-based software makes profiling incredibly simple for even the most advanced applications, providing intuitive set-up, multi-stage profiling, on-the-fly profile adjustment, flux-dipping, unlimited profile storage and much more.



Non-Contact IR Thermal Sensor

A closed-loop, non-contact IR temperature sensor monitors and controls the ramp-rate and temperature of the component in real time, by controlling the top and bottom heaters' output throughout the reflow process.

IR3100 Advanced Features

- **Non-Contact IR Thermal Sensor:** A closed-loop, non-contact IR temperature sensor monitors and controls the ramp-rate and temperature of the component in real time, by controlling the top and bottom heaters' output throughout the heating process.
- **Ultra-High Precision Placement Capability:** Motorized reflow head is driven by advanced stepper motor system providing smooth, high precision, repeatable movement with no drift, allowing for soft landing of components and 28µm (.0011") placement accuracy.
- **High Sensitivity Vacuum Pick:** New Vacuum Pick design is more robust, utilizes an optical sensor, is counterweight balanced, and employs precision high-temperature linear ball bearings for maximum accuracy and sensitivity in placement and pick-up.
- **Sodr-Cam Reflow Camera:** Provided Sodr-Cam allows the operator to verify the entire reflow process, including the exact moment of solder melt.
- **Height Adjustable Bottom-Side Preheater:** High powered (1000W) IR preheater height is adjustable from standard position up to 38mm (1.5") closer to the PCB for the most challenging high-thermal-mass boards.
- **High-Definition Optical Alignment System:** Automated Vision Overlay System uses a beam-splitting prism, high intensity LEDs for shadow-free lighting and a new high definition 1080p camera for easy alignment.
- **Quad-Field Imaging for Large/Fine Pitch BGA's:** Allows up to four corners of a large component (and its lands) to be viewed under high magnification, providing perfect alignment of outsized BGAs or fine-pitch QFPs.
- **Integrated Board Support Wand:** Prevents warping or sagging during reflow, is extremely adjustable to clear parts on the bottom of PCB and is easily removed when not in use.



www.paceworldwide.com

www.facebook.com/paceworldwide
www.youtube.com/paceworldwide

phone 910.695.7223
 toll free 877.882.7223 (PACE)
 fax 910.695.1594
 email support@paceworldwide.com



Leaders in the industry since 1958